

numeral 220 has been replaced with reference numeral 290 to designate a clamp shown in the Figure, and corresponding corrections to the specification, as set forth above, have been made. Acceptance of these proposed corrections is respectfully requested.

IN THE CLAIMS

Please amend claims 1 and 14 as follows:

Sub B5
1. (Amended) An assembly for holding a substrate, the substrate having a first surface, a second surface opposite the first surface, and an outer peripheral portion, said assembly comprising:
a holding body having a support surface for supporting the substrate, said holding body having an aperture for passing therethrough a gas having a first thermal conductivity; and
a heat transferring seal having a first surface for frictionally engaging said second surface of said substrate, said heat transferring seal having a second surface, opposite said first surface, for frictionally engaging said support surface of said holding body, said heat transferring seal having an inner peripheral portion defining an opening for receiving the gas, wherein said heat transferring seal has a second thermal conductivity [closely matched with the thermal conductivity of the gas, for providing substantially uniform heat transfer] and a cross-section configured to transfer heat to or from the substrate uniformly across the substrate.

A2
Sub B6
14. (Amended) A heat transferring seal for placing in an assembly for holding a substrate, said substrate having a first surface and a second surface opposite the first surface, said assembly including a holding body having a support surface for supporting the substrate, the holding body having an aperture for passing therethrough a gas having a first thermal conductivity, the heat transferring seal comprising:

6 a heat transferring seal having a first surface for frictionally engaging said second
7 surface of said substrate, said heat transferring seal having a second surface, opposite said
8 first surface, for frictionally engaging said support surface of said holding body, said heat
9 transferring seal having an inner peripheral portion defining an opening for receiving the gas,
10 wherein said heat transferring seal has a second thermal conductivity [closely matched with
11 the thermal conductivity of the gas, for providing substantially uniform heat transfer] and a
12 cross-section configured to transfer heat to or from the substrate uniformly across the
13 substrate.

REMARKS

Reconsideration of this application, as amended, is respectfully requested. As indicated, the specification has been corrected so that the clamp apparatus shown in Figure 2 is indicated by reference numeral 290 and not 220 which is used to designate the heat transfer seal. No new matter has been added. Also, claims 1 and 14 have been amended to more clearly recite the present invention. Support for these amendments may be found, for example, at p.7, ll. 13-16; and p. 8, l. 18-p. 9, l. 8. No new matter has been added.

The present claims are patentable over the cited art of record which fails to teach or suggest a heat transferring seal having a thermal conductivity and cross-section configured to transfer heat to or from the substrate uniformly across the substrate, as recited in claims 1 and 14. As noted in the specification at p. 9, such a heat transferring seal provides for more than separating the outer peripheral portion of a wafer from a holding body. It also provides a medium for transferring heat which allows for uniform heat transfer across the substrate.

Horiuchi et al., U.S. Patent No. 5,155,331, fails to teach or suggest the use of such a heat transferring seal. It is true that, Horiuchi et al. disclose the use of a sealing ring, however, the discussion of this sealing ring reads as follows:

Sealing ring 12 extends from the underside of insulating ring 11 to the peripheral rim of the underside of upper electrode 7. Sealing ring 12 is made of insulating material such as ethylene tetrafluoride resin in such a way that plasma can be generated